

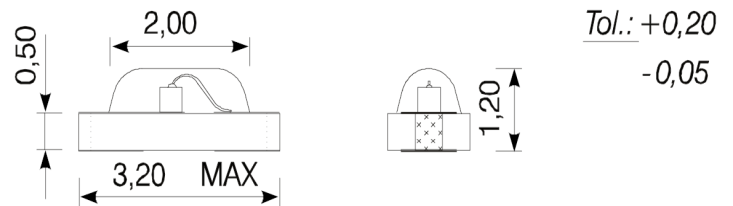
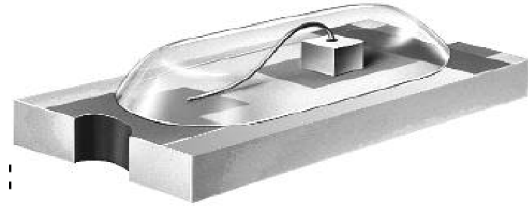
## CR50HR

### Features

- Solid State Ceramic Chip
- High Power Thermal Absorption
- Superior Light Uniformity Over 180°
- End-to-End and Side-to-Side Stackable to a pitch of 1.3mm
- Solderpads conform to Mil-Std 883B
- D-H Structure
- Hyper Red GaAlAs Material
- Water Clear Lens

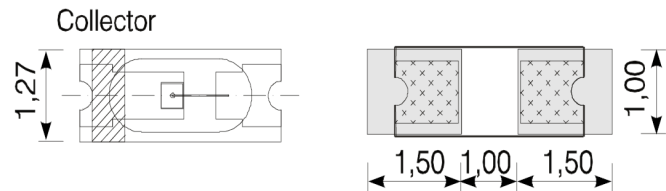
### Applications

- Ideal For Back-Light Applications
- Custom Configurations



### Maximum Ratings (Ta=25°C)

Characteristic	Symbol	Max.	Unit
Forward Current	I <sub>F</sub>	75	mA
Reverse Voltage	V <sub>R</sub>	10	V
Power Dissipation	P <sub>D</sub>	130.00	mW
Operating Temperature	T <sub>opr</sub>	-25 ~ +80	°C
Storage Temperature	T <sub>stg</sub>	-25 ~ +120	°C
Soldering Temperature	T <sub>sol</sub>	250	°C
Soldering Time	-	for 10 sec. max	-



### Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	-	1.80	2.10	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	-	100	μA
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =20mA	8.00	15.00	-	mcd
Viewing Angle	2θ <sup>1/2</sup>	-	-	180°	-	deg.
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =20mA	-	660	-	nm
Dominant Wavelength	λ <sub>d</sub>	I <sub>F</sub> =20mA	-	643	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> =20mA	-	20	-	nm

Specifications are Subject to Change Without Notice